

## 1. General description

Silicon Carbide Schottky diode in a DFN 8\*8 plastic package, designed for high frequency switched-mode power supplies.



## 2. Features and benefits

- Highly stable switching performance
- High forward surge capability IFSM
- Extremely fast reverse recovery time
- Superior in efficiency to Silicon Diode alternatives
- Reduced losses in associated MOSFET
- Reduced EMI
- Reduced cooling requirements
- RoHS compliant

## 3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives

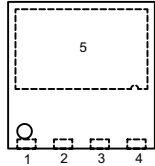
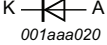
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values				Unit
Absolute maximum rating							
V <sub>RRM</sub>	repetitive peak reverse voltage		650				V
I <sub>F(AV)</sub>	average forward current	δ = 0.5 ; square-wave pulse; T <sub>c</sub> ≤ 150 °C; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	4				A
T <sub>j</sub>	junction temperature		175				°C
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 4 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 5</a>		-	1.5	1.7	V
		I <sub>F</sub> = 4 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 5</a>		-	1.8	2.1	V
Dynamic characteristics							
Q <sub>r</sub>	recovered charge	I <sub>F</sub> = 4 A; dI <sub>F</sub> /dt = 500 A/μs; V <sub>R</sub> = 400 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	7	-	nC

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	not connected		
2	n.c.	not connected		
3	A	anode		
4	A	anode		
5	K	mounting base; connected to cathode		

## 6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC04650T	DFN8*8	WNSC04650T6J	Tape	3000	DFN8X8N	25-Dec-2019

## 7. Marking

Table 4. Marking codes

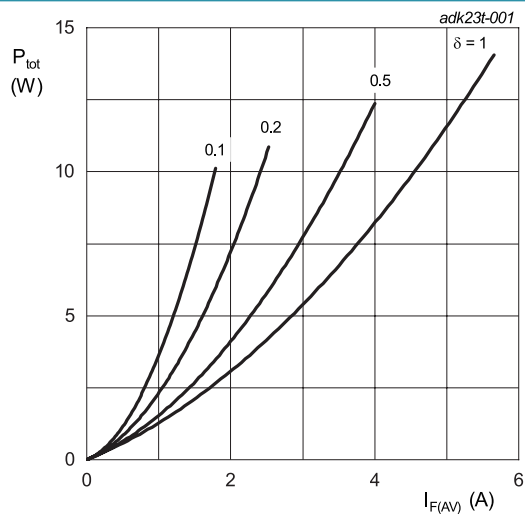
Type number	Marking codes
WNSC04650T	WNSC 04650T

## 8. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

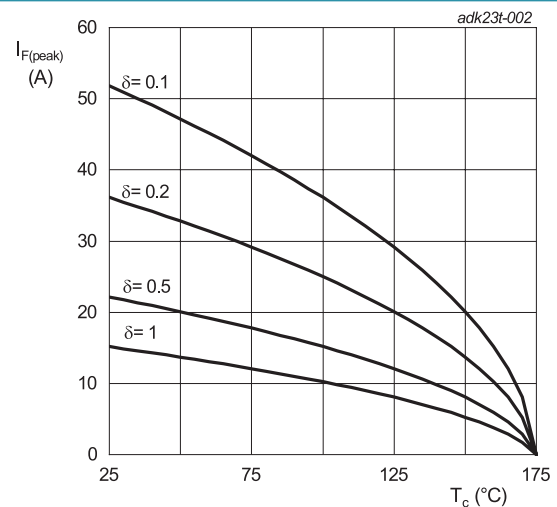
Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		650	V
$V_{RWM}$	crest working reverse voltage		650	V
$V_R$	reverse voltage	DC	650	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$ ; square-wave pulse; $T_c \leq 150\text{ }^{\circ}\text{C}$ ; Fig. 1; Fig. 2; Fig. 3	4	A
$I_{FRM}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25\text{ }\mu\text{s}$ ; $T_c \leq 150\text{ }^{\circ}\text{C}$ ; square-wave pulse	8	A
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10\text{ ms}$ ; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; sine-wave pulse	24	A
		$t_p = 10\text{ }\mu\text{s}$ ; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; square-wave pulse	235	A
$I^2t$	$I^2t$ for fusing	sine-wave pulse; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$ ; $t_p = 10\text{ ms}$	3	$\text{A}^2\text{s}$
$T_{stg}$	storage temperature		-55 to 175	$^{\circ}\text{C}$
$T_j$	junction temperature		175	$^{\circ}\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 1.017\text{ V}; R_s = 0.2593\text{ }\Omega$$

**Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values**



**Fig. 2. Current derating as a function of case temperature**

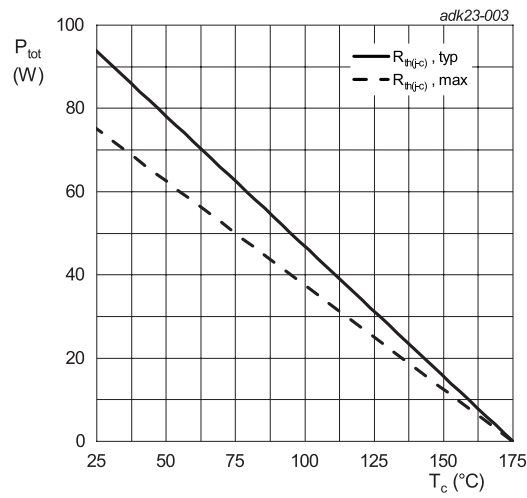


Fig. 3. Total power dissipation as a function of case temperature

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	<a href="#">Fig. 4</a>		-	1.6	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air		-	50	-	K/W

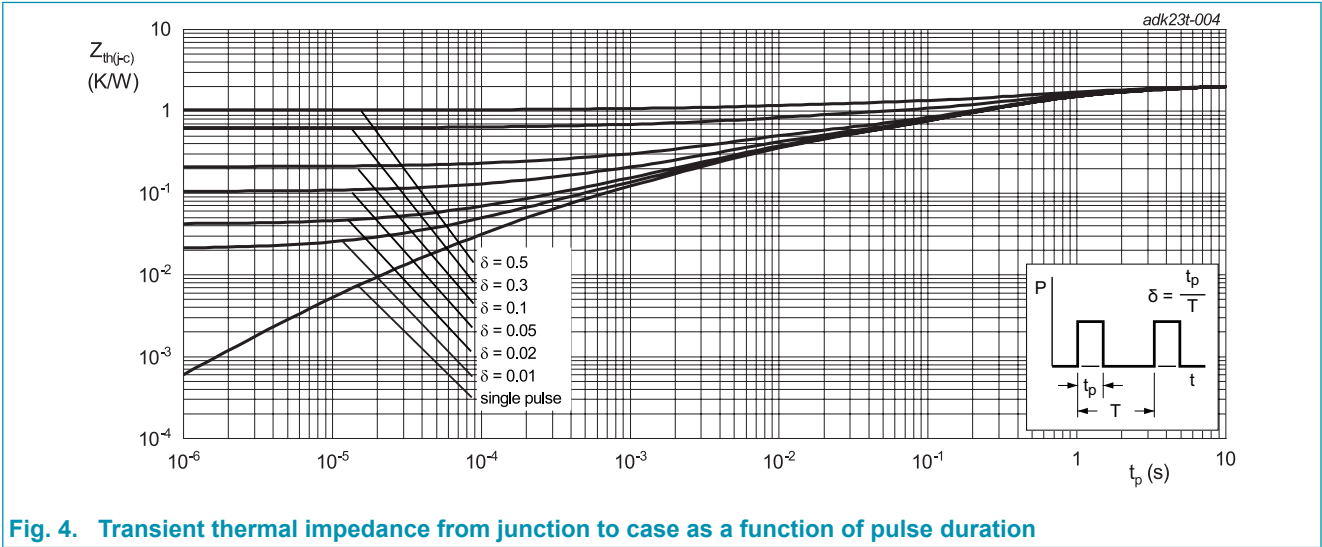
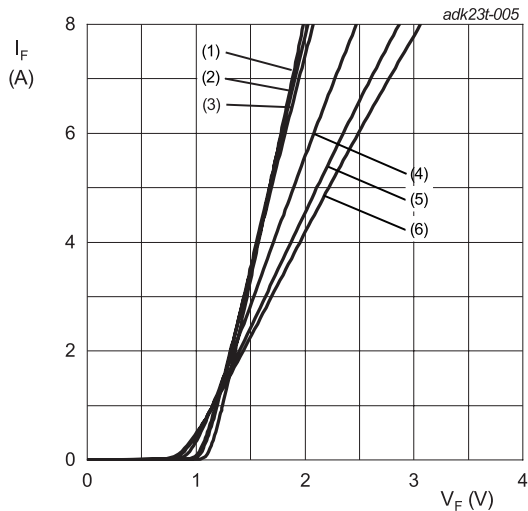


Fig. 4. Transient thermal impedance from junction to case as a function of pulse duration

## 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V <sub>F</sub>	forward current	I <sub>F</sub> = 4 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 5</a>		-	1.5	1.7	V
		I <sub>F</sub> = 4 A; T <sub>j</sub> = 150 °C; <a href="#">Fig. 5</a>		-	1.8	2.1	V
		I <sub>F</sub> = 4 A; T <sub>j</sub> = 175 °C; <a href="#">Fig. 5</a>			2	2.25	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 6</a>		-		25	μA
		V <sub>R</sub> = 650 V; T <sub>j</sub> = 175 °C; <a href="#">Fig. 6</a>		-		100	μA
Dynamic characteristics							
Q <sub>r</sub>	recovered charge	I <sub>F</sub> = 4 A; V <sub>R</sub> = 400 V; dI <sub>F</sub> /dt = 500 A/μs; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		-	7	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C		-	141	-	pF
		f = 1 MHz; V <sub>R</sub> = 300 V; T <sub>j</sub> = 25 °C		-	23	-	pF
		f = 1 MHz; V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C		-	22	-	pF
E <sub>as</sub>	non-repetitive avalanche energy	I <sub>R</sub> = 3.5 A; L = 5 mH; T <sub>j</sub> (init) = 25 °C		30	-	-	mJ



$V_o = 1.017\text{ V}; R_s = 0.2593\text{ }\Omega$

- (1)  $T_J = -55\text{ °C}$ ; typical values
- (2)  $T_J = 0\text{ °C}$ ; typical values
- (3)  $T_J = 25\text{ °C}$ ; typical values
- (4)  $T_J = 100\text{ °C}$ ; typical values
- (5)  $T_J = 150\text{ °C}$ ; typical values
- (6)  $T_J = 175\text{ °C}$ ; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

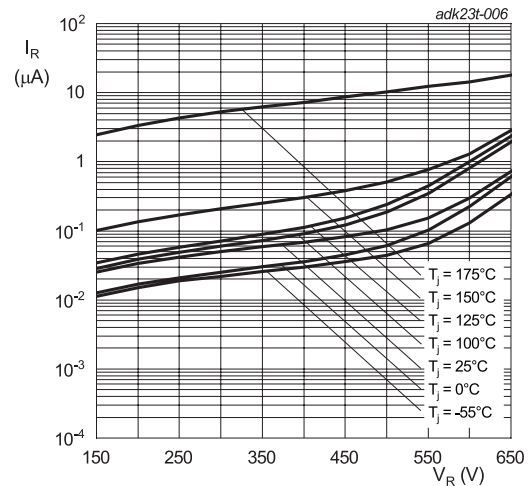


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

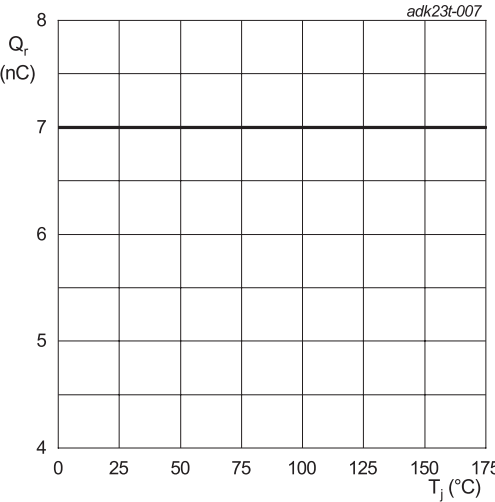
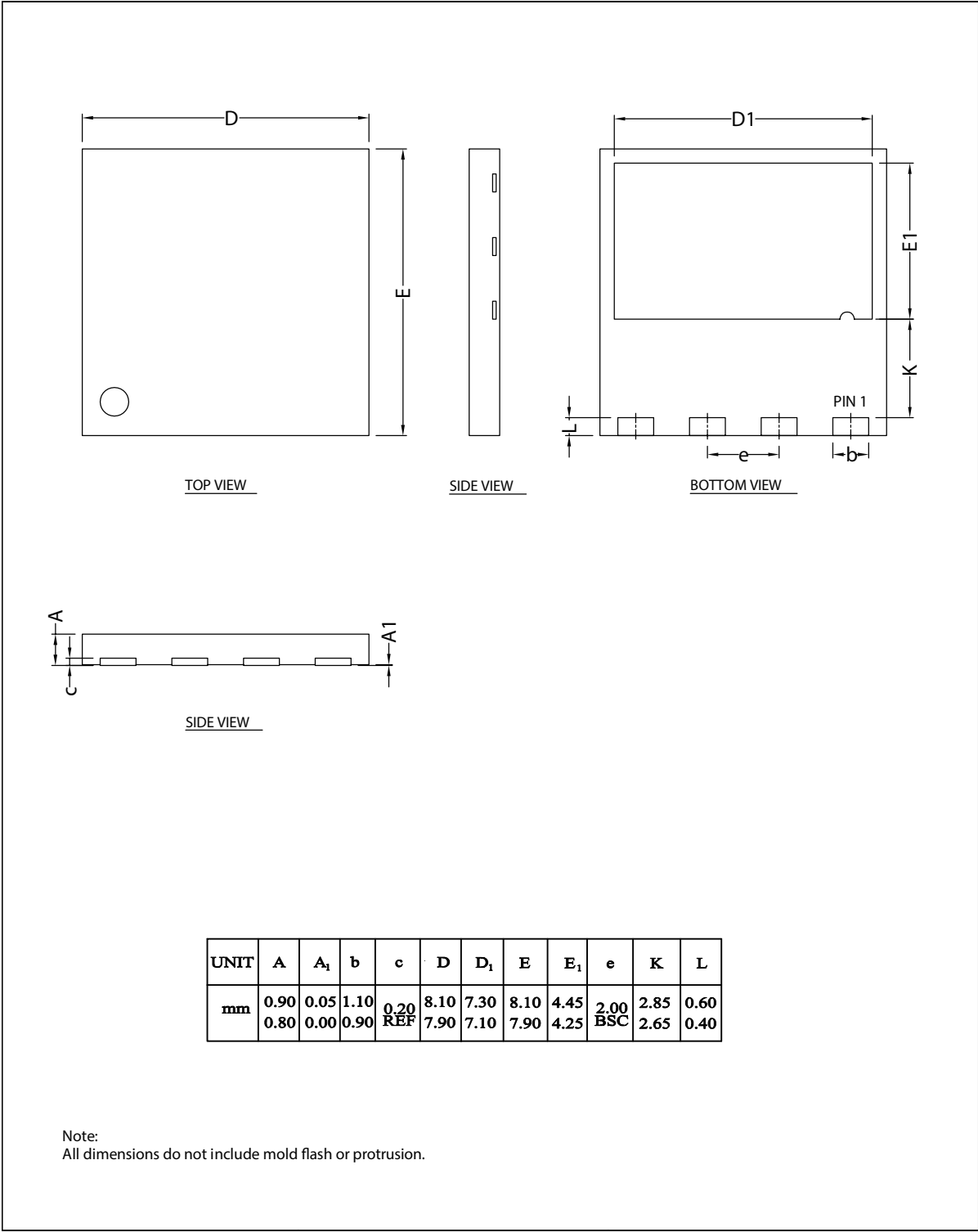


Fig. 7. Recovered charge as a function of junction temperature

11. Package outline





## 12. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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